



Product Change Notification / RMES-04ABMM740

Date:

05-Nov-2020

Product Category:

Ethernet PHYs, Ethernet Switches, PCIe - Signal Integrity

PCN Type:

Manufacturing Change

Notification Subject:

CCB 3740.003 Final Notice: Qualification of MTAI as an additional final test site for selected Microsemi ENT VSC331xx, VSC722xx, VSC742xx, VSC743xx, VSC744xx, VSC746xx, VSC825xx, VSC847xx, VSC848xx, VSC851xx and VSC866xx device families available in 48L VQFN, 256L PBGA, 672L HSBGA, 196L FCBGA and 195L / 244L / 256L / 672L HFCBGA packages.

Affected CPNs:

[RMES-04ABMM740_Affected_CPN_11052020.pdf](#)

[RMES-04ABMM740_Affected_CPN_11052020.csv](#)

Notification Text:

PCN Status: Final notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change: Qualification of MTAI as an additional final test site for selected Microsemi ENT VSC331xx, VSC722xx, VSC742xx, VSC743xx, VSC744xx, VSC746xx, VSC825xx, VSC847xx, VSC848xx, VSC851xx and VSC866xx device families available in 48L VQFN, 256L PBGA, 672L HSBGA, 196L FCBGA and 195L / 244L / 256L / 672L HFCBGA packages.

Pre Change:

Tested at ASE (ASE9) final test site

Post Change:

Tested at ASE (ASE9)

or

Tested at Microchip Technology Thailand (HQ) (MTAI) final test site

Pre and Post Change Summary:

		Pre Change	Post Change	
Final test site		ASE Test (ASE9)	ASE Test (ASE9)	Microchip Technology Thailand (HQ) (MTAI)
Base Quantity Multiple (BOM)	48L VQFN	364	364	364
	256L PBGA	84	84	84
	672L HSBGA	40	40	40
	672L HFCBGA	40	40	40
	256L HFCBGA	90	90	90
	244L HFCBGA	90	90	90
	195L HFCBGA	168	168	168
	196L FCBGA	126	126	126
Tray Stack		5+1	5+1	10+1
Tray		Bakeable (150°C)	Bakeable (150°C)	Bakeable (150°C)
Pin 1 Orientation		Chamfer Tray	Chamfer Tray	Chamfer Tray
Tray Dimension		No changes		

Impacts to Data Sheet: None**Change Impact:** None**Reason for Change:** To improve on-time delivery performance by qualifying MTAI as an additional final test site.**Change Implementation Status:** In Progress**Estimated First Ship Date:**December 05, 2020(date code: 2049)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	November 2020					December 2020			
Workweek	44	45	46	47	48	49	50	51	52
Qual Report Availability		X							
Final PCN Issue Date		X							
Estimated Implementation Date						X			

Method to Identify Change: Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: November 05, 2020: Issued final notification. Attached the qualification report and added estimated first ship date by December 05, 2020.

The change described in this PCN does not alter Microchip’s current regulatory compliance regarding the material content of the applicable products.

Attachments:

- [PCN_RMES-04ABMM740_Pre and Post Change Summary.pdf](#)
- [PCN_RMES-04ABMM740_Qual_Report.pdf](#)

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our **PCN home page** select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the **PCN FAQ** section.

If you wish to change your PCN profile, including opt out, please go to the **PCN home page** select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

RMES-04ABMM740 - CCB 3740.003 Final Notice: Qualification of MTAI as an additional final test site for selected Microsemi ENT VSC331xx, VSC722xx, VSC742xx, VSC743xx, VSC744xx, VSC746xx, VSC825xx, VSC847xx, VSC848xx, VSC851xx and VSC866xx device families available in 48L VQFN, 256L PBGA, 672L HSBGA, 196L FCBGA and 195L / 244L / 256L / 672L HFCBGA packages.

Affected Catalog Part Numbers (CPN)

VSC7224XJV-02
VSC7224XJV
VSC7224XJV-01
VSC7223XJV
VSC7420XJG-02
VSC7421XJG-02
VSC7422XJG-02
VSC7424XJG-02
VSC7425XJG-02
VSC7426XJG-02
VSC7427XJG-02
VSC8512XJG-02
VSC7420XJG-04
VSC7421XJG-04
VSC7422XJG-04
VSC7423XJG-02
VSC7424XJG-12
VSC7427XJG-12
VSC7428XJG-02
VSC7428XJG-12
VSC7429XJG-02
VSC8512XJG-03
VSC8254YMR
VSC8256YMR
VSC8257YMR
VSC8258YMR
VSC7438YIH-02
VSC7442YIH-02
VSC7444YIH-02
VSC7448YIH-02
VSC7449YIH-02
VSC7464YIH-02
VSC7468YIH-02
VSC7431YIH-01
VSC7432YIH-01
VSC7434YIH-01
VSC7460YIH
VSC7462YIH
VSC3316YYP
VSC3316YYP-60
VSC3312YYP-01
VSC3312YYP-31
VSC8479YHQ-01
VSC8479YHQ-02
VSC8479YYY
VSC8662XIC

RMES-04ABMM740 - CCB 3740.003 Final Notice: Qualification of MTAI as an additional final test site for selected Microsemi VSC331xx, VSC722xx, VSC742xx, VSC743xx, VSC744xx, VSC746xx, VSC825xx, VSC847xx, VSC848xx, VSC851xx and VSC866xx device families available in 48L VQFN, 256L PBGA, 672L HSBGA, 196L FCBGA and 195L / 244L / 256L / 672L HFCBGA packages.

VSC8662XIC-03

VSC8664XIC-03

VSC8486YSN-04

CCB 3740.003
Pre and Post Change Summary
PCN #: RMES-04ABMM740



A Leading Provider of Smart, Connected and Secure Embedded Control Solutions

**Qualification of MTAI as an additional final test site for selected
Microsemi ENT VSC331xx, VSC722xx, VSC742xx, VSC743xx, VSC744xx,
VSC746xx, VSC825xx, VSC847xx, VSC848xx, VSC851xx and VSC866xx
device families available in 48L VQFN, 256L PBGA, 672L HSBGA, 196L
FCBGA and 195L / 244L / 256L / 672L HFCBGA packages.**



SMART | CONNECTED | SECURE

Pre and Post Change Summary

PACKAGE		PRE CHANGE	POST CHANGE	
	Final test site	ASE Test (ASE9)	ASE Test (ASE9)	Microchip Technology Thailand (HQ) (MTAI)
48L VQFN	Base Quantity Multiple (BQM)	364	364	364
	Tray Stack	5+1	5+1	10+1
	Tray	Bakeable (150°C)	Bakeable (150°C)	Bakeable (150°C)
	Pin 1 Orientation	Chamfer Tray	Chamfer Tray	Chamfer Tray
256L PBGA	Base Quantity Multiple (BQM)	84	84	84
	Tray Stack	5+1	5+1	10+1
	Tray	Bakeable (150°C)	Bakeable (150°C)	Bakeable (150°C)
	Pin 1 Orientation	Chamfer Tray	Chamfer Tray	Chamfer Tray
672L HSBGA	Base Quantity Multiple (BQM)	40	40	40
	Tray Stack	5+1	5+1	10+1
	Tray	Bakeable (150°C)	Bakeable (150°C)	Bakeable (150°C)
	Pin 1 Orientation	Chamfer Tray	Chamfer Tray	Chamfer Tray

Pre and Post Change Summary

PACKAGE		PRE CHANGE	POST CHANGE	
Final test site		ASE Test (ASE9)	ASE Test (ASE9)	Microchip Technology Thailand (HQ) (MTAI)
672L HFCBGA	Base Quantity Multiple (BQM)	40	40	40
	Tray Stack	5+1	5+1	10+1
	Tray	Bakeable (150°C)	Bakeable (150°C)	Bakeable (150°C)
	Pin 1 Orientation	Chamfer Tray	Chamfer Tray	Chamfer Tray
256L HFCBGA	Base Quantity Multiple (BQM)	90	90	90
	Tray Stack	5+1	5+1	10+1
	Tray	Bakeable (150°C)	Bakeable (150°C)	Bakeable (150°C)
	Pin 1 Orientation	Chamfer Tray	Chamfer Tray	Chamfer Tray
244L HFCBGA	Base Quantity Multiple (BQM)	90	90	90
	Tray Stack	5+1	5+1	10+1
	Tray	Bakeable (150°C)	Bakeable (150°C)	Bakeable (150°C)
	Pin 1 Orientation	Chamfer Tray	Chamfer Tray	Chamfer Tray

Pre and Post Change Summary

PACKAGE		PRE CHANGE	POST CHANGE	
Final test site		ASE Test (ASE9)	ASE Test (ASE9)	Microchip Technology Thailand (HQ) (MTAI)
195L HFCBGA	Base Quantity Multiple (BQM)	168	168	168
	Tray Stack	5+1	5+1	10+1
	Tray	Bakeable (150°C)	Bakeable (150°C)	Bakeable (150°C)
	Pin 1 Orientation	Chamfer Tray	Chamfer Tray	Chamfer Tray
196L FCBGA	Base Quantity Multiple (BQM)	126	126	126
	Tray Stack	5+1	5+1	10+1
	Tray	Bakeable (150°C)	Bakeable (150°C)	Bakeable (150°C)
	Pin 1 Orientation	Chamfer Tray	Chamfer Tray	Chamfer Tray



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QUALIFICATION REPORT SUMMARY

PCN #: RMES-04ABMM740

Date

September 24, 2020

Qualification of MTAI as an additional final test site for selected Microsemi ENT products available in 138L QFN package. Microsemi ENT VSC331xx, VSC722xx, VSC742xx, VSC743xx, VSC744xx, VSC746xx, VSC825xx, VSC847xx, VSC848xx, VSC851xx and VSC866xx device families available in 48L VQFN, 256L PBGA, 672L HSBGA, 196L FCBGA and 195L / 244L / 256L / 672L HFCBGA packages will qualify by similarity.

Purpose: Qualification of MTAI as an additional final test site for selected Microsemi ENT products available in 138L QFN package. Microsemi ENT VSC331xx, VSC722xx, VSC742xx, VSC743xx, VSC744xx, VSC746xx, VSC825xx, VSC847xx, VSC848xx, VSC851xx and VSC866xx device families available in 48L VQFN, 256L PBGA, 672L HSBGA, 196L FCBGA and 195L / 244L / 256L / 672L HFCBGA packages will qualify by similarity.

CCB No.: 3740, 3740.001, 3740.002 and 3740.003

Test / Evaluation	Test Conditions / Parameters	Result
Test comparison	<ul style="list-style-type: none"> • Select 50 good sample - test using the original platform and retest using destination platform. • The selected measured parameter should be within +/-10% variation between original and destination platform. 	Passed
Fresh lot run	<ul style="list-style-type: none"> • Select 1 fresh lot. Lot quantity is 3,000 units. Test using the new test location platform. Then cross correlate with original test location platform. • Bin to bin difference should be within 0.1%. 	Passed